

# March 2009 SuperFET<sup>™</sup>

## FCA35N60 600V N-Channel MOSFET

### Features

- 650V @ T<sub>J</sub> = 150°C
- Typ.R<sub>DS(on)</sub> = 0.079Ω
- Ultra low gate charge ( Typ. Q<sub>g</sub> = 139nC )
- Low effective output capacitance (Typ. C<sub>oss</sub>.eff = 340pF )
- 100% avalanche tested

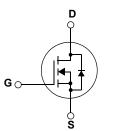


## Description

SuperFET<sup>TM</sup> is Farichild's proprietary, new generation of high voltage MOSFET family that is utilizing an advanced charge balance mechanism for outstanding low on-resistance and lower gate charge performance.

This advanced technology has been tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate and higher avalanche energy. Consequently, SuperFET is very suitable for various AC/DC power conversion in switching mode operation for system miniaturization and higher efficiency.





### MOSFET Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted\*

	Ratings	Units			
Drain to Source Voltage	600	V			
Gate-Soure voltage			±30	V	
Drain Current	-Continuous (T <sub>C</sub> = 25 <sup>o</sup> C)	-Continuous ( $T_C = 25^{\circ}C$ )		A	
DrainCurrent	-Continuous (T <sub>C</sub> = 100 <sup>o</sup> C)		22.2	A	
Drain Current	- Pulsed	- Pulsed (Note 1)		Α	
Single Pulsed Avalanche Er	(Note 2)	1455	mJ		
Avalanche Current		(Note 1)	35	А	
Repetitive Avalanche Energy		(Note 1)	31.25	mJ	
Peak Diode Recovery dv/dt		(Note 3)	20	V/ns	
Dower Dissinction	(T <sub>C</sub> = 25°C)	$(T_{\rm C} = 25^{\rm o}{\rm C})$		W	
Power Dissipation	- Derate above 25°C		2.5	W/ºC	
Operating and Storage Temperature Range			-55 to +150	°C	
Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds			300	°C	
	Gate-Soure voltage   Gate-Soure voltage   Drain Current   Single Pulsed Avalanche En   Avalanche Current   Repetitive Avalanche Energ   Peak Diode Recovery dv/dt   Power Dissipation   Operating and Storage Tem   Maximum Lead Temperature	Gate-Soure voltage   Gate-Soure voltage   Drain Current -Continuous ( $T_C = 25^{\circ}C$ )   Drain Current - Pulsed   Single Pulsed Avalanche Energy   Avalanche Current   Repetitive Avalanche Energy   Peak Diode Recovery dv/dt   Power Dissipation   ( $T_C = 25^{\circ}C$ )   Operating and Storage Temperature Range   Maximum Lead Temperature for Soldering Purpose,	$\begin{tabular}{ c c c c } \hline Drain to Source Voltage & & & & & & & & & & & & & & & & & & &$	$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	

### **Thermal Characteristics**

Symbol	Parameter	Тур.	Max.	Units
$R_{ ext{ heta}JC}$	Thermal Resistance, Junction to Case	-	0.4	
$R_{\theta CS}$	Thermal Resistance, Case-to-Heat Sink	0.24	-	°C/W
$R_{\thetaJA}$	Thermal Resistance, Junction to Ambient	-	42	

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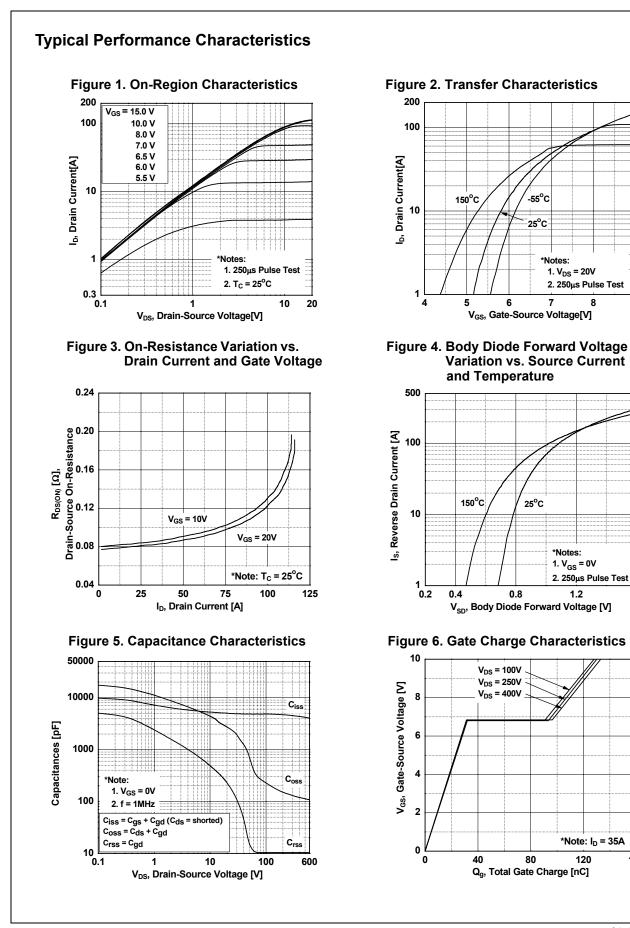
<u> </u>		Packa	ige	Reel Size	Таре	Width		Quantit	у	
		TO-3F	PN	-		-		30		
Electrica	l Char	acteristics								
Symbol		Parameter			Test Conditions		Min.	Тур.	Max.	Units
- Off Charac	teristic	S							I	
				I <sub>D</sub> = 28	50μA, V <sub>GS</sub> = 0V, T <sub>J</sub> =	25°C	600	-	-	V
BV <sub>DSS</sub>			/oltage	$I_{\rm D} = 250 \mu A, V_{\rm GS} = 0V, T_{\rm J} = 150^{\circ} {\rm C}$		-	650	-	V	
ΔBV <sub>DSS</sub> ′ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient		ture	$I_D = 250 \mu A$ , Referenced to $25^{\circ}C$			-	0.6	-	V/ºC
BV <sub>DS</sub>	Drain-Source Avalanche Breakdown Voltage		akdown	V <sub>GS</sub> = 0V, I <sub>D</sub> = 16A			-	700	-	V
DSS	Zero G	ate Voltage Drain Curi	rent	V <sub>DS</sub> = 600V, V <sub>GS</sub> = 0V			-	-	1	μA
033		<b>.</b>		$V_{DS} = 480V, T_{C} = 125^{\circ}C$			-	-	10	
I <sub>GSS</sub>	Gate to	Body Leakage Curre	nt	V <sub>GS</sub> =	±30V, V <sub>DS</sub> = 0V		-	-	±100	nA
On Charac	teristic	S								
V <sub>GS(th)</sub>	Gate T	hreshold Voltage			$V_{DS}$ , $I_D = 250 \mu A$		3.0	-	5.0	V
R <sub>DS(on)</sub>	Static D	Static Drain to Source On Resistance			10V, I <sub>D</sub> = 17.5A		-	0.079	0.098	Ω
9 <sub>FS</sub>	Forward Transconductance			V <sub>DS</sub> = 40V, I <sub>D</sub> = 17.5A			-	28.8	-	S
Dynamic C	Charact	eristics								
C <sub>iss</sub>	Input Capacitance					-	4990	6640	pF	
C <sub>oss</sub>	Output	Capacitance		— V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V — f = 1MHz		-	2380	3170	pF	
C <sub>rss</sub>	Revers	e Transfer Capacitanc	e		11 12	ſ	-	140	-	pF
C <sub>oss</sub>	Output	Capacitance		V <sub>DS</sub> =	480V, $V_{GS}$ = 0V, f = 1	.0MHz	-	113	-	pF
C <sub>oss</sub> eff.	Effectiv	e Output Capacitance	$V_{DS}$ = 0V to 480V, $V_{GS}$ = 0V		-	340	-	pF		
Qg	Total G	ate Charge at 10V				-	139	181	nC	
Q <sub>gs</sub>	Gate to	Source Gate Charge			V <sub>DS</sub> = 480V, I <sub>D</sub> = 35A V <sub>GS</sub> = 10V		-	31	-	nC
Q <sub>gd</sub>	Gate to	Drain "Miller" Charge		(Note 4)		-	69	-	nC	
ESR	Equivalent Series Resistance (G-S)		Drain Open, F= 1MHZ			-	1.4	-	Ω	
Switching	Charac	teristics								
t <sub>d(on)</sub>		n Delay Time					-	34	78	ns
t <sub>r</sub>		n Rise Time			300V, I <sub>D</sub> = 35A		-	120	250	ns
t <sub>d(off)</sub>	Turn-Of	f Delay Time		R <sub>G</sub> = 4	4.7Ω	_	-	105	220	ns
t <sub>f</sub>	Turn-Of	ff Fall Time		(Note 4)		(Note 4)	-	73	155	ns
Drain-Sou	rce Dio	de Characteristic	s							
I <sub>S</sub>	Maximu	m Continuous Drain to	o Source Dio	de Forwa	rd Current		-	-	35	А
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode F		urce Diode Fo	orward C	urrent		-	-	105	Α
V <sub>SD</sub>	Drain to	Source Diode Forwar	rd Voltage	V <sub>GS</sub> =	0V, I <sub>SD</sub> = 35A		-	-	1.4	V
	Reverse	e Recovery Time			0V, I <sub>SD</sub> = 35A		-	614	-	ns
Q <sub>rr</sub>	Reverse	e Recovery Charge		$dI_{F}/dt = 100A/\mu s$		-	16.3	-	μC	

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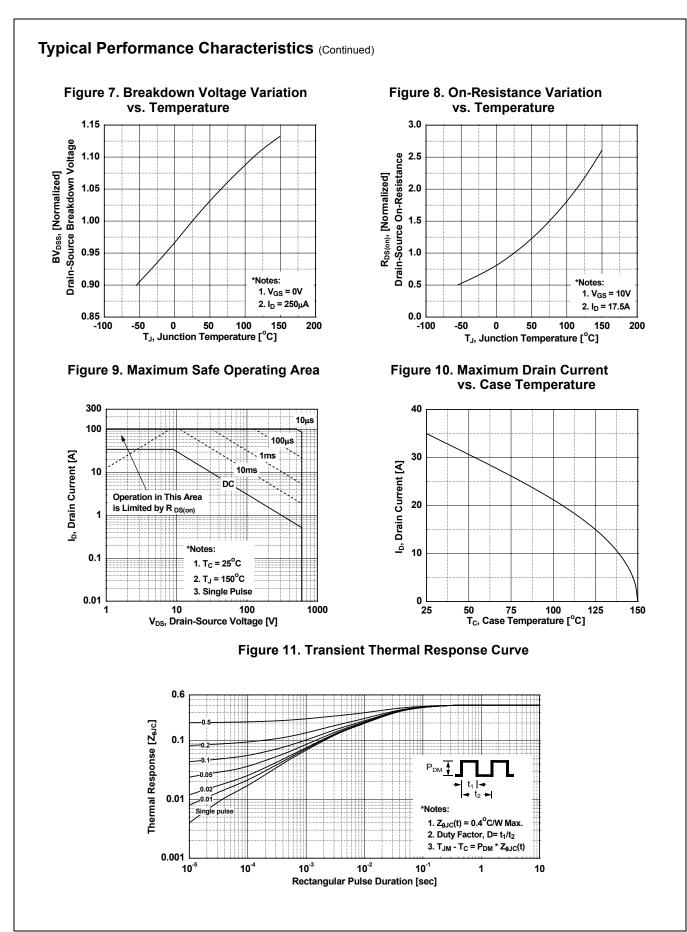
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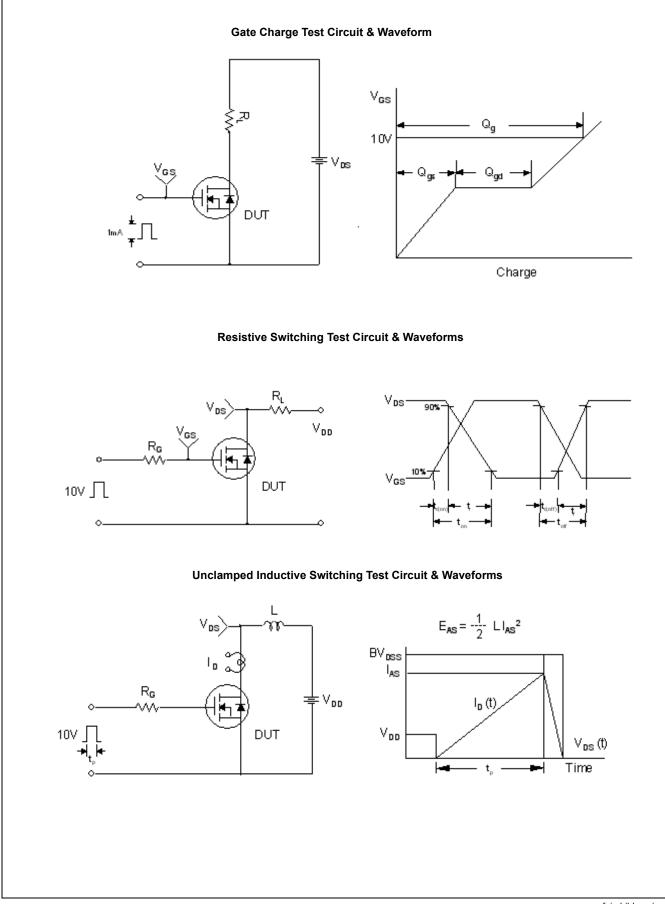


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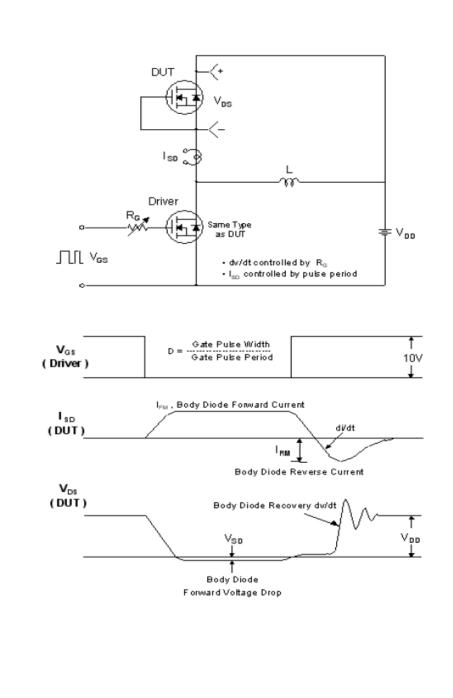
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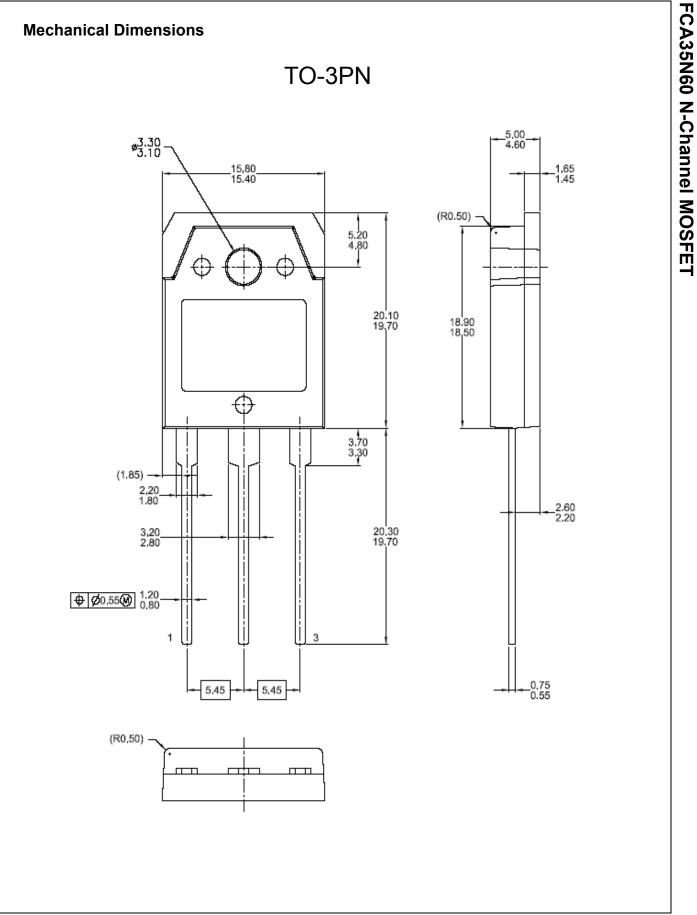


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### Peak Diode Recovery dv/dt Test Circuit & Waveforms







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